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Substitute for form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (use as many sheets as necessary)		<i>Complete If Known</i>	
		Application Number	10/034,528
		First Named Inventor	Eldridge et al.
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		Group Art Unit	2829
		Examiner Name	Paresh H. Patel
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	277	KR	10-0013608 (Previously Submitted 5/25/04)		Tokyo Electron co.	6-Sep-90	Yes	
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		Office <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup>				
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	279	WO	1989/007258		The Board of Trustees of the Leland Stanford Junior University	10-Aug-98	Yes	
	280	WO	1990/000735		University of Hawaii	25-Jan-90	Yes	
	281	WO	1990/008397		The Board of Trustees of the Leland Stanford Junior University	26-Jul-90	Yes	
	282	WO	1990/015517		Labinal Components & Systems, Inc.	13-Dec-90	Yes	
	283	WO	1991/005284		British Telecommunications Public Limited Company	18-Apr-91	Yes	
	284	WO	1992/020842		Cornell Research Foundation, Inc.	16-Nov-92	Yes	
	285	WO	1993/018382		Kopin Corporation	16-Sep-93	Yes	
	286	WO	1994/012887		Micromodule Systems, Inc.	9-Jun-94	Yes	
	287	WO	1994/029671		DANISCH, Lee, A..	22-Dec-94	Yes	
	288	WO	1997/009584		IBM Corporation	13-Mar-97	Yes	
	289	WO	1998/026300		GGB Industries, Inc.	18-Jun-98	Yes	

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	290	"Probe Card Stiffener With Theta Adjust," IBM Technical Bulletin (2 pages) (no publication information)			Yes
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	292	BARSOTTI C., et al. "Very High Density Probing," (Tektronix), 1988 International Test Conference, pp.608-614, (1988).			Yes
	293	BEILEY Mark et al., "A Micromachined Array Probe Card-Characterization," IEEE Transactions on Components, Packaging, and manufacturing Tehcnology - Part B, Vol. 18, No.1, pp.184-191, February 1995.			Yes
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	298	Hirano T. et al, "Silicon Microprobing Array for Testing and Burn-In," (IEEE), pp.89-94, July 1994.	Yes	
	299	KIEWITT D.A., "Microtool fabrication by etch pit replication." Rev. Sci. Instrum., Vol.44, No.12, pp.1741-1742, 1973.	Yes	
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	302	MACHIDA K., "Interconnect Technology of the 1990s", Surface Mount Technology, pp. 3-12.	Yes	
	303	MILOSEVIC I. et al., "Straight Wall Bumps for High Lead Count Devices: Photolithography and Physical Properties", Materials Research Society Symposium Proceedings, Vol. 154, pp.425-440, 1989.	Yes	
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	307	YOUNKIN L., "Thin-Film-Hybrid Wafer-Probe Card Promises Speed and Density," Electronics Test, pp. 26-30, May 1989.	Yes	
	308	"Phicom Corporation's Amended Invalidity And Unenforceability Contentions," FormFactor, Inc. v. Phicom Corporation, United States District Court District of Oregon (Case No. 05-6062-HO)	Yes	
	309	"Defendants' Patent Local Rule 3-3 Preliminary Invalidity Contentions For U.S. Patent Nos. 6,246,247, 6,509,751, 6,624,648, And 7,073,254," FormFactor, Inc. v. Micronics Japan Co. and MJC Electronics Corp., United States District Court Northern District of California (Case No. 3:06-CV-07159 JSW)	Yes	

Examiner Signature		Date Considered	
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